# onsemi

# Silicon Carbide (SiC) MOSFET - EliteSiC, 40 mohm, 1200 V, M3S, D2PAK-7L NVBG040N120M3S

### **Features**

- Typ.  $R_{DS(on)} = 40 \text{ m}\Omega @ V_{GS} = 18 \text{ V}$
- Ultra Low Gate Charge  $(Q_{G(tot)} = 75 \text{ nC})$
- High Speed Switching with Low Capacitance ( $C_{oss} = 80 \text{ pF}$ )
- 100% Avalanche Tested
- AEC-Q101 Qualified and PPAP Capable
- This Device is Halide Free and RoHS Compliant with exemption 7a, Pb–Free 2LI (on second level interconnection)

### **Typical Applications**

- Automotive On Board Charger
- Automotive DC/DC Converter for EV/HEV

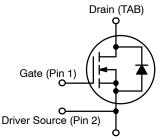
### **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			$V_{DSS}$	1200	V
Gate-to-Source Voltage	Gate-to-Source Voltage			-10/+22	V
	Recommended Operation Values of Gate-to-Source Voltage		$V_{GSop}$	-3/+18	٧
Continuous Drain Current (Notes 2, 3)	Steady State	T <sub>C</sub> = 25°C	I <sub>D</sub>	57	Α
Power Dissipation (Note 2)			P <sub>D</sub>	263	W
Continuous Drain Current (Notes 2, 3)	Steady State	T <sub>C</sub> = 100°C	I <sub>D</sub>	40	Α
Power Dissipation (Note 2)			P <sub>D</sub>	131	W
Pulsed Drain Current (Note 4)	T <sub>C</sub> = 25°C		I <sub>DM</sub>	149	Α
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C
Source Current (Body Diode) T <sub>C</sub> = 25°C, V <sub>GS</sub> = -3 V (Note 2)			I <sub>S</sub>	50	Α
Single Pulse Drain-to-Source Avalanche Energy (I <sub>L(pk)</sub> = 16.9 A, L = 1 mH) (Note 5)			E <sub>AS</sub>	143	mJ
Maximum Temperature for Soldering (10 s)			$T_L$	270	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Surface mounted on a FR-4 board using1 in<sup>2</sup> pad of 2 oz copper.
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 3. The maximum current rating is based on typical RDS(on) performance.
- 4. Repetitive rating, limited by max junction temperature.
- 5.  $E_{AS}$  of 143 mJ is based on starting  $T_J$  = 25°C; L = 1 mH,  $I_{AS}$  = 16.9 A,  $V_{DD}$  = 100 V,  $V_{GS}$  = 18 V.

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
1200 V	54 mΩ @ 18 V	57 A



Power Source (Pins 3, 4, 5, 6, 7)

### **N-CHANNEL MOSFET**



D2PAK-7L CASE 418BJ

### **MARKING DIAGRAM**

BG040N 120M3S AYWWZZ

BG040N120M3S = Specific Device Code

A = Assembly Location

Y = Year WW = Work Week ZZ = Lot Traceability

### **ORDERING INFORMATION**

Device	Package	Shipping
NVBG040N120M3S	D2PAK-7L	800 / Tape & Reel

### THERMAL CHARACTERISTICS

Ī	Parameter	Symbol	Max	Unit
	Junction-to-Case - Steady State (Note 2)	$R_{\theta JC}$	0.57	°C/W
ſ	Junction-to-Ambient - Steady State (Notes 1, 2)	$R_{\theta JA}$	40	

### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
OFF-STATE CHARACTERISTICS	1		ı			ı
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	1200	_	-	V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>	I <sub>D</sub> = 1 mA, referenced to 25°C (Note 7)	-	0.3	-	V/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 1200 V	-	-	100	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = +22/-10 V, V <sub>DS</sub> = 0 V	-	-	±1	μΑ
ON-STATE CHARACTERISTICS						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}$ , $I_D = 10 \text{ mA}$	2.04	2.9	4.4	V
Recommended Gate Voltage	$V_{GOP}$		-3	-	+18	V
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 18 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 25°C	-	40	54	mΩ
		V <sub>GS</sub> = 18 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 175°C (Note 7)	-	80	-	
Forward Transconductance	9FS	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 20 A (Note 7)	-	16	-	S
CHARGES, CAPACITANCES & GATE RES	SISTANCE				•	
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1 MHz, V <sub>DS</sub> = 800 V	-	1700	-	pF
Output Capacitance	C <sub>OSS</sub>		-	80	-	
Reverse Transfer Capacitance	C <sub>RSS</sub>		-	7	-	
Total Gate Charge	Q <sub>G(TOT)</sub>	$V_{GS} = -3/18 \text{ V}, V_{DS} = 800 \text{ V},$ $I_{D} = 20 \text{ A}$	-	75	-	nC
Threshold Gate Charge	Q <sub>G(TH)</sub>	I <sub>D</sub> = 20 A	-	4.4	-	1
Gate-to-Source Charge	Q <sub>GS</sub>		-	14	-	
Gate-to-Drain Charge	$Q_{GD}$		-	22	-	
Gate-Resistance	$R_{G}$	f = 1 MHz	-	3.8	_	Ω
SWITCHING CHARACTERISTICS	•				•	
Turn-On Delay Time	t <sub>d(ON)</sub>	$V_{GS} = -3/18 \text{ V},$	-	13	_	ns
Rise Time	t <sub>r</sub>	V <sub>DS</sub> = 800 V, I <sub>D</sub> = 20 A,	-	16	_	
Turn-Off Delay Time	t <sub>d(OFF)</sub>	$R_G = 4.7 \Omega$ inductive load (Notes 6, 7)	-	38	_	
Fall Time	t <sub>f</sub>		-	10	_	
Turn-On Switching Loss	E <sub>ON</sub>		-	193	_	μJ
Turn-Off Switching Loss	E <sub>OFF</sub>		-	66	-	1
Total Switching Loss	E <sub>tot</sub>		-	259	_	
SOURCE-DRAIN DIODE CHARACTERISTICS						
Continuous Source-Drain Diode Forward Current (Note 2)	I <sub>SD</sub>	$V_{GS} = -3 \text{ V, } T_C = 25^{\circ}\text{C}$ (Note 7)	-	-	50	Α
Pulsed Source–Drain Diode Forward Current (Note 4)	I <sub>SDM</sub>		-	-	149	
Forward Diode Voltage	$V_{SD}$	V <sub>GS</sub> = −3 V, I <sub>SD</sub> = 20 A, T <sub>J</sub> = 25°C	-	4.5	_	V

### **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise specified) (continued)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
SOURCE-DRAIN DIODE CHARACTER		1001 00114111011		1.76		
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = -3/18 \text{ V}, I_{SD} = 20 \text{ A},$ $dI_S/dt = 1000 \text{ A}/\mu\text{s}, V_{DS} = 800 \text{ V}$	_	16.8	_	ns
Reverse Recovery Charge	Q <sub>RR</sub>	di <sub>S</sub> /dt = 1000 A/μs, V <sub>DS</sub> = 800 V (Note 7)	_	82	-	nC
Reverse Recovery Energy	E <sub>REC</sub>		_	7.9	_	μJ
Peak Reverse Recovery Current	I <sub>RRM</sub>		_	9.8	-	Α
Charge time	t <sub>A</sub>		_	9.6	_	ns
Discharge time	t <sub>B</sub>	1	_	7.2	_	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

6. E<sub>ON</sub>/E<sub>OFF</sub> result is with body diode

7. Defined by design, not subject to production test.

### **TYPICAL CHARACTERISTICS**

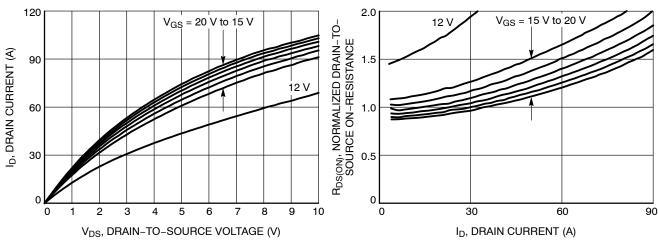


Figure 1. On-Region Characteristics

Figure 2. Normalized On–Resistance vs. Drain Current and Gate Voltage

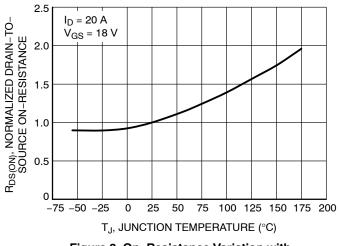


Figure 3. On–Resistance Variation with Temperature

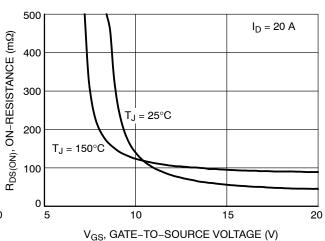


Figure 4. On-Resistance vs. Gate-to-Source Voltage

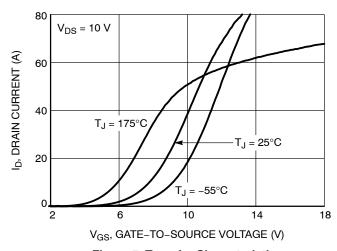


Figure 5. Transfer Characteristics

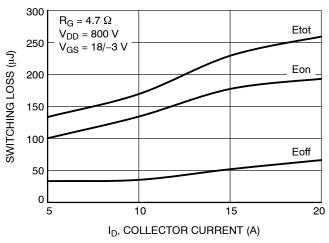


Figure 6. Switching Loss vs. Collector Current

### **TYPICAL CHARACTERISTICS**

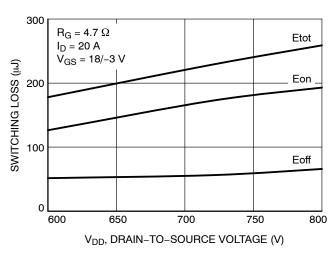


Figure 7. Switching Loss vs. Drain-to-Source Voltage

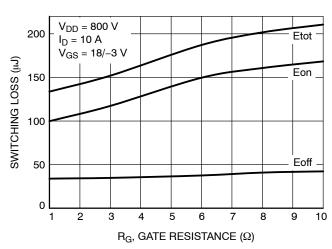


Figure 8. Switching Loss vs. Gate Resistance

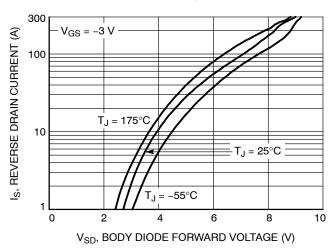


Figure 9. Reverse Drain Current vs. Body Diode Forward Voltage

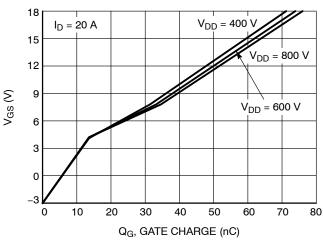


Figure 10. Gate-to-Source Voltage vs. Total Charge

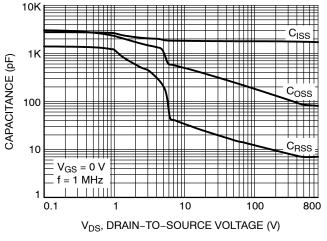


Figure 11. Capacitance vs. Drain-to-Source Voltage

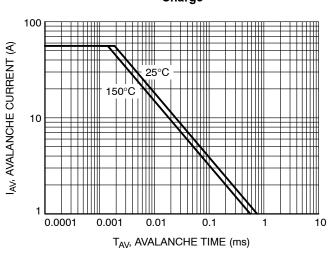


Figure 12. Unclamped Inductive Switching Capability

### **TYPICAL CHARACTERISTICS**

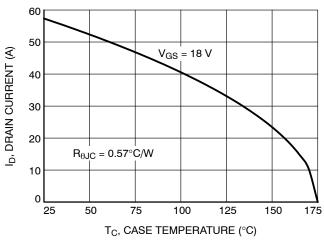


Figure 13. Maximum Continuous Drain Current vs. Case Temperature

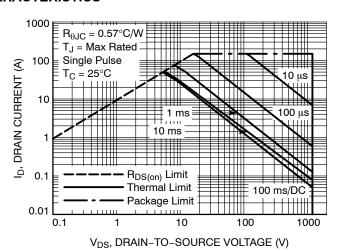


Figure 14. Safe Operating Area

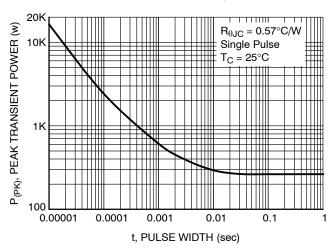


Figure 15. Single Pulse Maximum Power Dissipation

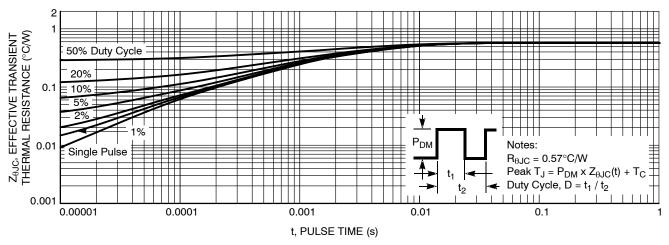
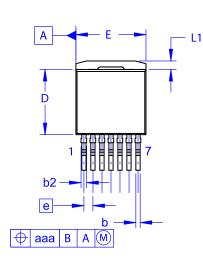
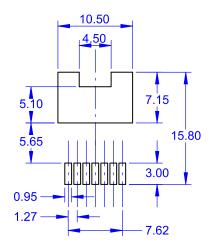


Figure 16. Junction-to-Case Transient Thermal Response

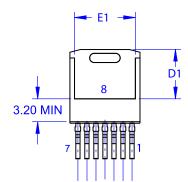
### **PACKAGE DIMENSIONS**

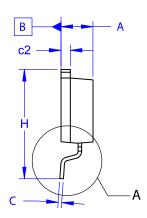
### D<sup>2</sup>PAK7 (TO-263-7L HV) CASE 418BJ **ISSUE B**





LAND PATTERN RECOMMENDATION





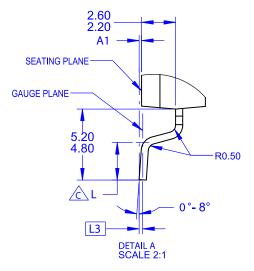
### NOTES:

- A. PACKAGE CONFORMS TO JEDEC TO-263 VARIATION CB EXCEPT WHERE NOTED. B. ALL DIMENSIONS ARE IN MILLIMETERS.
- OUT OF JEDEC STANDARD VALUE.

  D. DIMENSION AND TOLERANCE AS PER ASME
  Y14.5-2009.

  E. DIMENSIONS ARE EXCLUSIVE OF BURRS,
  MOLD FLASH AND TIE BAR PROTRUSIONS.

DIM	MIL	LIMETER	S
DIM	MIN	NOM	MAX
Α	4.30	4.50	4.70
<b>A</b> 1	0.00	0.10	0.20
b2	0.60	0.70	0.80
b	0.51	0.60	0.70
С	0.40	0.50	0.60
c2	1.20	1.30	1.40
D	9.00	9.20	9.40
D1	6.15	6.80	7.15
Е	9.70	9.90	10.20
E1	7.15	7.65	8.15
е	~	1.27	7
Н	15.10	15.40	15.70
L	2.44	2.64	2.84
L1	1.00	1.20	1.40
L3	~	0.25	~
aaa	~	~	0.25



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